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# RENESAS SEMICONDUCTOR RELIABILITY REPORT

- GROUP : RA6M1
- DEVICE : R7FA6M1XXX
- APPLICATION : Consumer / Industry

Quality Assurance Div. Renesas Electronics Corporation



MCR-22-0259

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### Table. Reliability test results (QFP)

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 ℃, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 ℃, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 ℃, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	=-65 °C to 150 °C , 300 cycles 0/22		
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time 0/3		Class: 2
Electrostatic discharge (ESD-CDM)	JESD22-C101	/-500V,1time 0/3		Class: C2
Solderability (SD)	J-STD-002	245 ℃, 5 s, Solder coverage ≥95 % 0/5		
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3)	0/22	

\*1) With preconditioning per JESD22-A113, MSL 3 •It is tested to confirm that all the samples are satisfied with an individual product specification.

Note :

Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .



### Table. Reliability test results (QFN)

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 ℃, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 ℃, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 ℃, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-65 ℃ to 150 ℃ , 300 cycles	∙65 ℃ to 150 ℃ , 300 cycles 0/22	
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time 0/3		Class: 2
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500V,1time 0/3		Class: C2
Solderability (SD)	J-STD-002	245 °C, 5 s, Solder coverage ≥95 % 0/5		
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3)	0/22	

\*1) With preconditioning per JESD22-A113, MSL 3 •It is tested to confirm that all the samples are satisfied with an individual product specification.

Note :

Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .



### Table. Reliability test results (LGA)

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 ℃, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 ℃, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 ℃, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-55 ℃ to 125 ℃ , 500 cycles	0/22	
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time	0/3	Class: 2
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500V,1time 0/3		Class: C2
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3)	0/22	

\*1) With preconditioning per JESD22-A113, MSL 3 •It is tested to confirm that all the samples are satisfied with an individual product specification.

Note :

Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .



The failure rate of the device in an actual use condition can be estimated by the below procedure.

#### • Equation for the failure rate estimation ( $\lambda$ )

 $\lambda = \lambda b \times \pi T$  (FIT)

**(1)**Unique failure rate ( $\lambda$ b)

λb= 0.08 FIT

Unique failure rate at Ta=55  $^{\circ}$ C using 60  $^{\circ}$  confidence level.

②Temperature term ( $\pi$ T)

 $\pi$  T=exp{11600×Ea×(1/(273+55)-1/(273+Ta))}

Ea: Activation energy (eV)

Ta : Ambient temperature ( $^{\circ}$ C)

$\pi$ T simplified chart as Ea=0.7 eV												
Ta (℃)	40	50	55	60	65	70	75	80	85	90	100	110
πΤ	0.31	0.68	1	1.45	2.08	2.95	4.15	5.77	7.96	10.88	19.82	34.99

## •MTTF ( Mean Time To Failure )

 $MTTF = 1/\lambda$ 



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#### Reference about Renesas package code

Package type	Package code *1	
Lead type plastic package	QFP	PxQP
Non-lead type plastic package	QFN	PxQN
Grid array type plastic package	BGA	PxBG
	LGA	PxLG

\*1. First four digit

#### Table. Product list

No	Group	Product part number	Package code	No	Group	Product part number	Package code
1	RA6M1	R7FA6M1AD3CFM	PLQP0064K*	51	0.000		. denage code
2	RA6M1	R7FA6M1AD3CFP	PLQP0100K*	52			
3	RA6M1	R7FA6M1AD2CLJ	PTLG0100J*	53			
4	RA6M1	R7FA6M1AD3CLJ	PTLG0100J*	54			
5	RA6M1	R7FA6M1AD3CNB	PWQN0064L*	55			
6				56			
7				57			
8				58			
9				59			
10				60			
11				61			
12				62			
13				63			
14				64			
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37				87			
38				88			
39 40				89 90			
41				91			
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49				99			
50				100			